

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
26 January 2023 (26.01.2023)



(10) International Publication Number
WO 2023/001827 A1

(51) International Patent Classification:
H01L 41/313 (2013.01)

(21) International Application Number:
PCT/EP2022/070204

(22) International Filing Date:
19 July 2022 (19.07.2022)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
FR2107785 19 July 2021 (19.07.2021) FR

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE,
KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU,
LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ,
UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,
TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
KM, ML, MR, NE, SN, TD, TG).

(54) Title: METHOD OF IMPLANTING ATOMIC SPECIES INTO A PIEZOELECTRIC SUBSTRATE

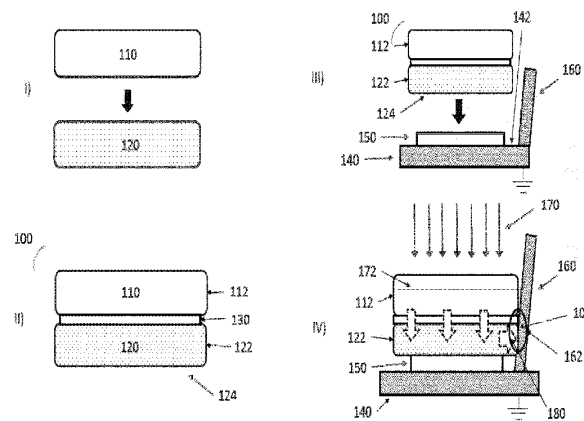


Figure 1

(57) Abstract: The invention relates to a method of implanting atomic species into a piezoelectric substrate, comprising the steps of I) providing a substrate (100, 200, 300) comprising a piezoelectric portion (112, 210, 310) and an electrically conductive portion (122, 320), III) mounting the substrate (100, 200, 300) with the electrically conductive portion (122, 320) over a chuck (140), and IV) implanting atomic species (170) into the piezoelectric portion (112, 210, 310).

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Published:

— *with international search report (Art. 21(3))*